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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	3100
Total RAM Bits	56320
Number of I/O	145
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfec3e-5q208c

Signed and Unsigned with Different Widths

The DSP block supports different widths of signed and unsigned multipliers besides x9, x18 and x36 widths. For unsigned operands, unused upper data bits should be filled to create a valid x9, x18 or x36 operand. For signed two's complement operands, sign extension of the most significant bit should be performed until x9, x18 or x36 width is reached. Table 2-8 provides an example of this.

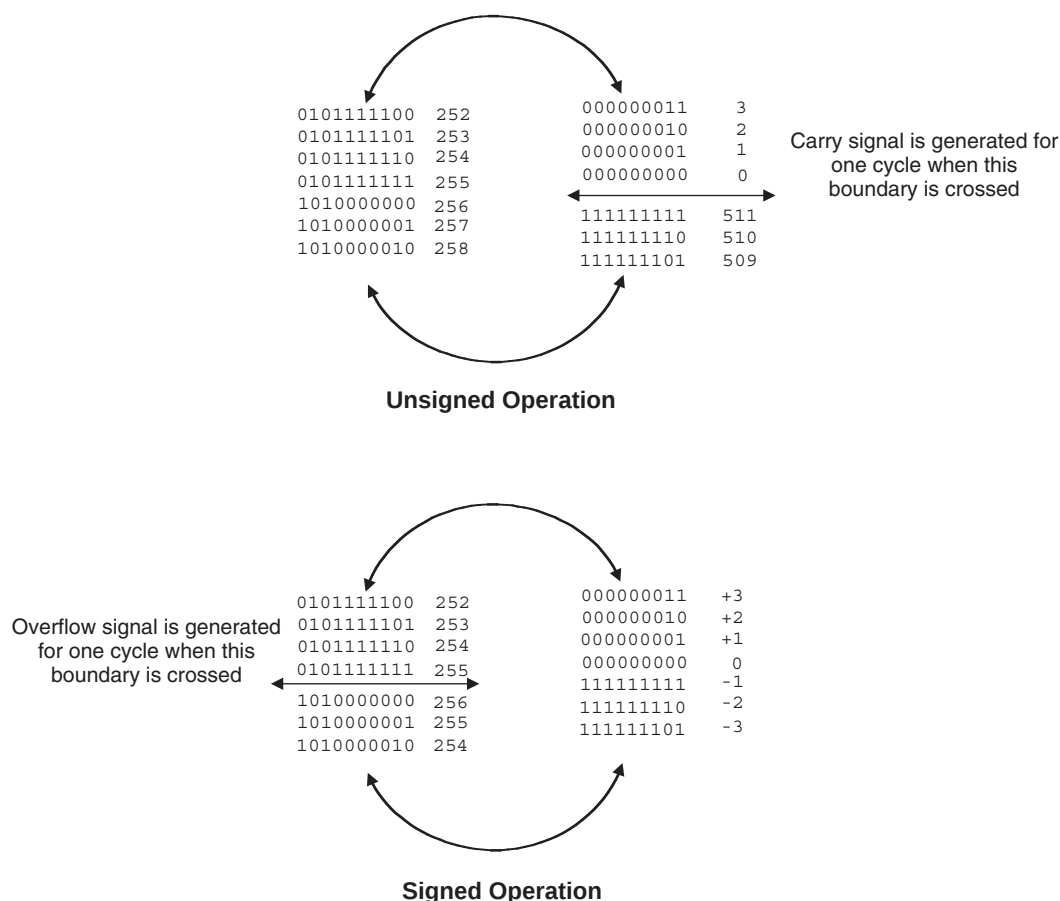
Table 2-8. An Example of Sign Extension

Number	Unsigned	Unsigned 9-bit	Unsigned 18-bit	Signed	Two's Complement Signed 9-Bits	Two's Complement Signed 18-bits
+5	0101	000000101	000000000000000101	0101	000000101	000000000000000101
-6	0110	000000110	000000000000000110	1010	111111010	111111111111111010

OVERFLOW Flag from MAC

The sysDSP block provides an overflow output to indicate that the accumulator has overflowed. When two unsigned numbers are added and the result is a smaller number then accumulator roll over is said to occur and overflow signal is indicated. When two positive numbers are added with a negative sum and when two negative numbers are added with a positive sum, then the accumulator “roll-over” is said to have occurred and an overflow signal is indicated. Note when overflow occurs the overflow flag is present for only one cycle. By counting these overflow pulses in FPGA logic, larger accumulators can be constructed. The conditions overflow signals for signed and unsigned operands are listed in Figure 2-23.

Figure 2-23. Accumulator Overflow/Underflow Conditions



IPexpress™

The user can access the sysDSP block via the IPexpress configuration tool, included with the ispLEVER design tool suite. IPexpress has options to configure each DSP module (or group of modules) or through direct HDL instantiation. Additionally Lattice has partnered Mathworks to support instantiation in the Simulink tool, which is a Graphical Simulation Environment. Simulink works with ispLEVER and dramatically shortens the DSP design cycle in Lattice FPGAs.

Optimized DSP Functions

Lattice provides a library of optimized DSP IP functions. Some of the IPs planned for LatticeECP DSP are: Bit Correlators, Fast Fourier Transform, Finite Impulse Response (FIR) Filter, Reed-Solomon Encoder/ Decoder, Turbo Encoder/Decoders and Convolutional Encoder/Decoder. Please contact Lattice to obtain the latest list of available DSP IPs.

Resources Available in the LatticeECP Family

Table 2-9 shows the maximum number of multipliers for each member of the LatticeECP family. Table 2-10 shows the maximum available EBR RAM Blocks in each of the LatticeECP family. EBR blocks, together with Distributed RAM can be used to store variables locally for the fast DSP operations.

Table 2-9. Number of DSP Blocks in LatticeECP Family

Device	DSP Block	9x9 Multiplier	18x18 Multiplier	36x36 Multiplier
LFCEP6	4	32	16	4
LFCEP10	5	40	20	5
LFCEP15	6	48	24	6
LFCEP20	7	56	28	7
LFCEP33	8	64	32	8

Table 2-10. Embedded SRAM in LatticeECP Family

Device	EBR SRAM Block	Total EBR SRAM (Kbits)
LFCEP6	10	92
LFCEP10	30	276
LFCEP15	38	350
LFCEP20	46	424
LFCEP33	54	498

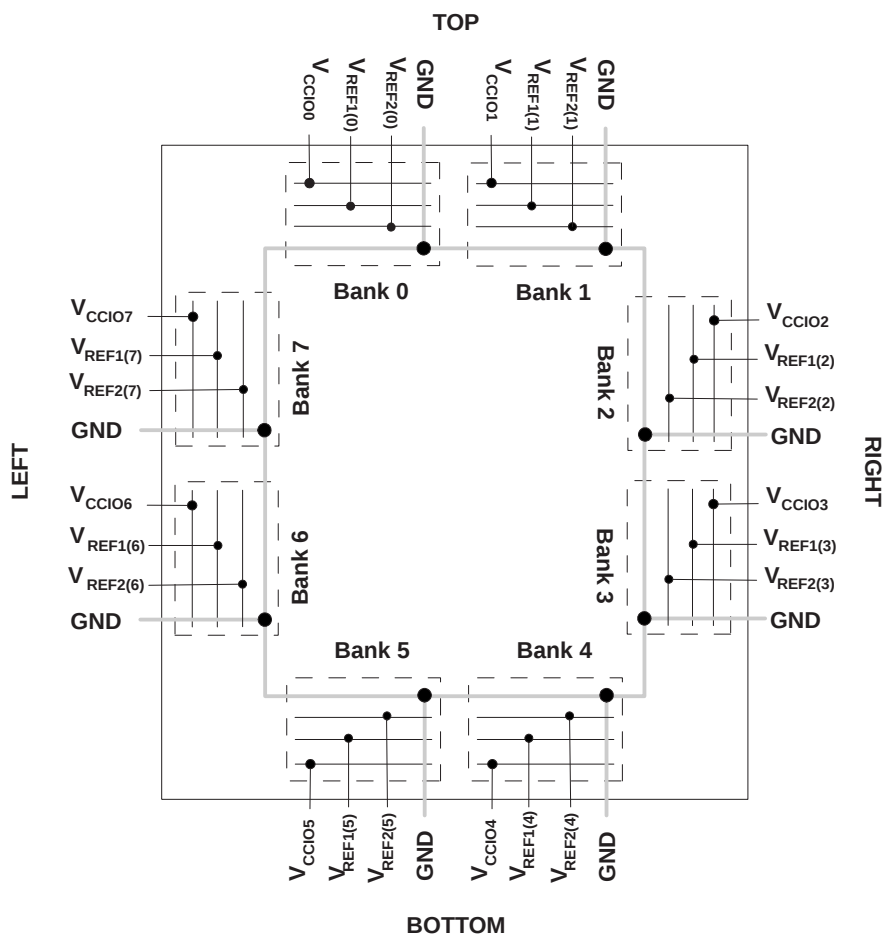
DSP Performance of the LatticeECP Family

Table 2-11 lists the maximum performance in millions of MAC operations per second (MMAC) for each member of the LatticeECP family.

Table 2-11. DSP Block Performance of LatticeECP Family

Device	DSP Block	DSP Performance MMAC
LFCEP6	4	3680
LFCEP10	5	4600
LFCEP15	6	5520
LFCEP20	7	6440
LFCEP33	8	7360

Figure 2-34. LatticeECP/EC Banks



LatticeECP/EC devices contain two types of sysI/O buffer pairs.

1. **Top and Bottom sysI/O Buffer Pairs (Single-Ended Outputs Only)**

The sysI/O buffer pairs in the top and bottom banks of the device consist of two single-ended output drivers and two sets of single-ended input buffers (both ratioed and referenced). The referenced input buffer can also be configured as a differential input.

The two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential input buffer and the comp (complementary) pad is associated with the negative side of the differential input buffer.

Only the I/Os on the top and bottom banks have programmable PCI clamps. These I/O banks also support hot socketing with I_{DK} less than 1mA. Note that the PCI clamp is enabled after V_{CC} , V_{CCAUX} and V_{CCIO} are at valid operating levels and the device has been configured.

2. **Left and Right sysI/O Buffer Pairs (Differential and Single-Ended Outputs)**

The sysI/O buffer pairs in the left and right banks of the device consist of two single-ended output drivers, two sets of single-ended input buffers (both ratioed and referenced) and one differential output driver. The referenced input buffer can also be configured as a differential input. In these banks the two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential I/O, and the comp (complementary) pad is associated with the negative side of the differential I/O.

Only the left and right banks have LVDS differential output drivers. See the I_{DK} specification for I/O leakage current during power-up.

be shifted in and loaded directly onto test nodes, or test data to be captured and shifted out for verification. The test access port consists of dedicated I/Os: TDI, TDO, TCK and TMS. The test access port has its own supply voltage V_{CCJ} and can operate with LVCMOS3.3, 2.5, 1.8, 1.5 and 1.2 standards.

For more details on boundary scan test, please see information regarding additional technical documentation at the end of this data sheet.

Device Configuration

All LatticeECP/EC devices contain two possible ports that can be used for device configuration. The test access port (TAP), which supports bit-wide configuration, and the sysCONFIG port that supports both byte-wide and serial configuration.

The TAP supports both the IEEE Std. 1149.1 Boundary Scan specification and the IEEE Std. 1532 In-System Configuration specification. The sysCONFIG port is a 20-pin interface with six of the I/Os used as dedicated pins and the rest being dual-use pins (please refer to TN1053 for more information about using the dual-use pins as general purpose I/O). There are four configuration options for LatticeECP/EC devices:

1. Industry standard SPI memories.
2. Industry standard byte wide flash and ispMACH 4000 for control/addressing.
3. Configuration from system microprocessor via the configuration bus or TAP.
4. Industry standard FPGA board memory.

On power-up, the FPGA SRAM is ready to be configured with the sysCONFIG port active. The IEEE 1149.1 serial mode can be activated any time after power-up by sending the appropriate command through the TAP port. Once a configuration port is selected, that port is locked and another configuration port cannot be activated until the next power-up sequence.

For more information about device configuration, please see the list of technical documentation at the end of this data sheet.

Internal Logic Analyzer Capability (ispTRACY)

All LatticeECP/EC devices support an internal logic analyzer diagnostic feature. The diagnostic features provide capabilities similar to an external logic analyzer, such as programmable event and trigger condition and deep trace memory. This feature is enabled by Lattice's ispTRACY. The ispTRACY utility is added into the user design at compile time.

For more information about ispTRACY, please see information regarding additional technical documentation at the end of this data sheet.

External Resistor

LatticeECP/EC devices require a single external, 10K ohm +/- 1% value between the XRES pin and ground. Device configuration will not be completed if this resistor is missing. There is no boundary scan register on the external resistor pad.

DC Electrical Characteristics

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I_{IL}, I_{IH}^1	Input or I/O Leakage	$0 \leq V_{IN} \leq (V_{CCIO} - 0.2V)$	—	—	10	μA
$I_{IH}^{1,3}$	Input or I/O High Leakage	$(V_{CCIO} - 0.2V) \leq V_{IH} \leq 3.6V$	—	—	40	μA
I_{PU}	I/O Active Pull-up Current	$0 \leq V_{IN} \leq 0.7 V_{CCIO}$	-30	—	-150	μA
I_{PD}	I/O Active Pull-down Current	$V_{IL} (MAX) \leq V_{IN} \leq V_{IH} (MAX)$	30	—	150	μA
I_{BHLS}	Bus Hold Low sustaining current	$V_{IN} = V_{IL} (MAX)$	30	—	—	μA
I_{BHHS}	Bus Hold High sustaining current	$V_{IN} = 0.7V_{CCIO}$	-30	—	—	μA
I_{BHLO}	Bus Hold Low Overdrive current	$0 \leq V_{IN} \leq V_{IH} (MAX)$	—	—	150	μA
I_{BHLH}	Bus Hold High Overdrive current	$0 \leq V_{IN} \leq V_{IH} (MAX)$	—	—	-150	μA
V_{BHT}	Bus Hold trip Points	$0 \leq V_{IN} \leq V_{IH} (MAX)$	$V_{IL} (MAX)$	—	$V_{IH} (MIN)$	V
C1	I/O Capacitance ²	$V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V,$ $V_{CC} = 1.2V, V_{IO} = 0 \text{ to } V_{IH} (MAX)$	—	8	—	pf
C2	Dedicated Input Capacitance ²	$V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V,$ $V_{CC} = 1.2V, V_{IO} = 0 \text{ to } V_{IH} (MAX)$	—	6	—	pf

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tri-stated. It is not measured with the output driver active. Bus maintenance circuits are disabled.

2. T_A 25°C, $f = 1.0MHz$

3. For top and bottom general purpose I/O pins, when V_{IH} is higher than V_{CCIO} , a transient current typically of 30ns in duration or less with a peak current of 6mA can occur on the high-to-low transition. For left and right I/O banks, V_{IH} must be less than or equal to V_{CCIO} .

Differential HSTL and SSTL

Differential HSTL and SSTL outputs are implemented as a pair of complementary single-ended outputs. All allowable single-ended output classes (class I and class II) are supported in this mode.

LVDS25E

The top and bottom side of LatticeECP/EC devices support LVDS outputs via emulated complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs. The scheme shown in

Figure 3-1 is one possible solution for point-to-point signals.

Figure 3-1. LVDS25E Output Termination Example

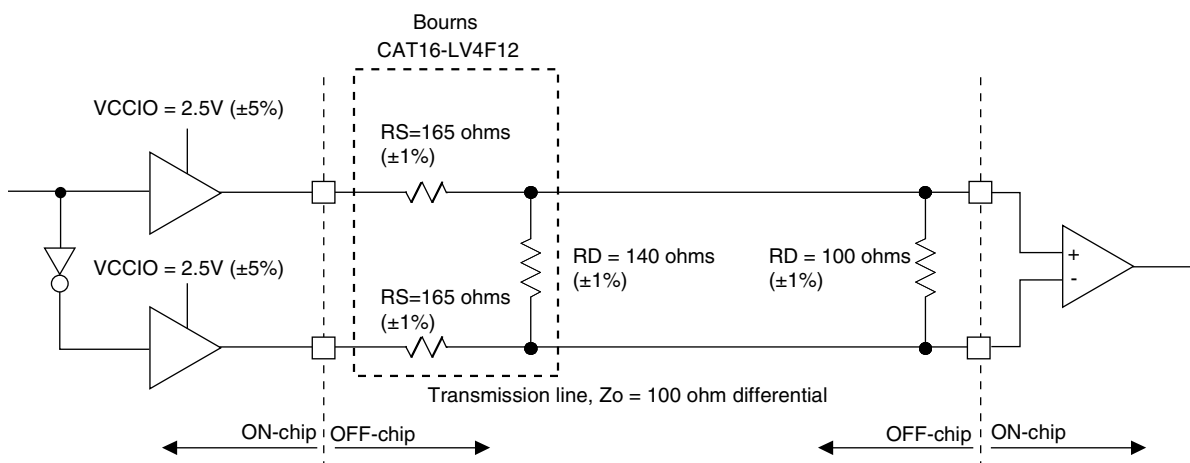


Table 3-1. LVDS25E DC Conditions

Parameter	Description	Typical	Units
V_{OH}	Output high voltage	1.42	V
V_{OL}	Output low voltage	1.08	V
V_{OD}	Output differential voltage	0.35	V
V_{CM}	Output common mode voltage	1.25	V
Z_{BACK}	Back impedance	100	$\%$

LVPECL

The LatticeECP/EC devices support differential LVPECL standard. This standard is emulated using complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs. The LVPECL input standard is supported by the LVDS differential input buffer. The scheme shown in Figure 3-3 is one possible solution for point-to-point signals.

Figure 3-3. Differential LVPECL

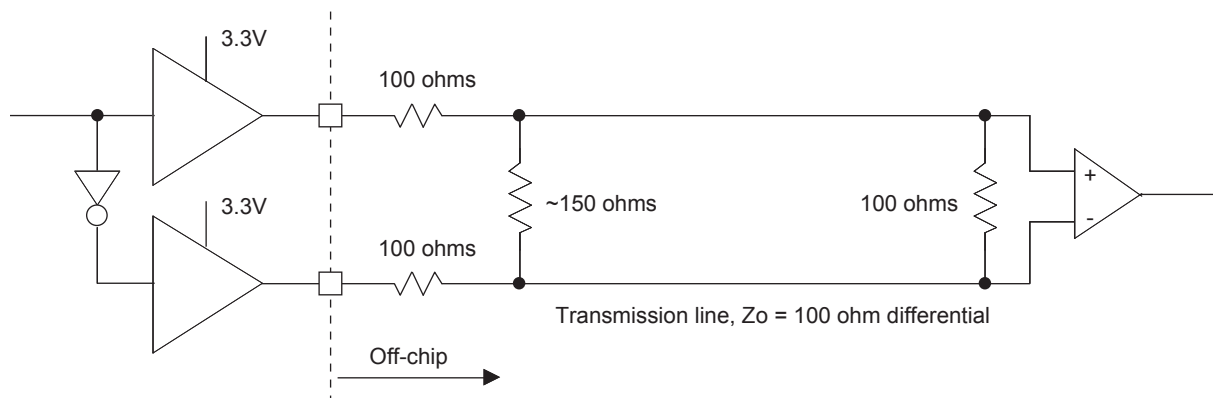


Table 3-3. LVPECL DC Conditions¹

Over Recommended Operating Conditions

Parameter	Description	Typical	Units
Z_{OUT}	Output impedance	100	ohm
R_P	Driver parallel resistor	150	ohm
R_T	Receiver termination	100	ohm
V_{OH}	Output high voltage	2.03	V
V_{OL}	Output low voltage	1.27	V
V_{OD}	Output differential voltage	0.76	V
V_{CM}	Output common mode voltage	1.65	V
Z_{BACK}	Back impedance	85.7	ohm
I_{DC}	DC output current	12.7	mA

1. For input buffer, see LVDS table.

For further information about LVPECL, BLVDS and other differential interfaces please see the list of technical information at the end of this data sheet.

LatticeECP/EC Family Timing Adders^{1, 2, 3} (Continued)

Over Recommended Operating Conditions

Buffer Type	Description	-5	-4	-3	Units
HSTL15_II	HSTL_15 class II	0.10	0.12	0.14	ns
HSTL15_III	HSTL_15 class III	0.10	0.12	0.14	ns
HSTL15D_I	Differential HSTL 15 class I	0.08	0.10	0.11	ns
HSTL15D_III	Differential HSTL 15 class III	0.10	0.12	0.14	ns
SSTL33_I	SSTL_3 class I	-0.05	-0.06	-0.07	ns
SSTL33_II	SSTL_3 class II	0.40	0.48	0.56	ns
SSTL33D_I	Differential SSTL_3 class I	-0.05	-0.06	-0.07	ns
SSTL33D_II	Differential SSTL_3 class II	0.40	0.48	0.56	ns
SSTL25_I	SSTL_2 class I	0.05	0.07	0.08	ns
SSTL25_II	SSTL_2 class II	0.25	0.30	0.35	ns
SSTL25D_I	Differential SSTL_2 class I	0.05	0.07	0.08	ns
SSTL25D_II	Differential SSTL_2 class II	0.25	0.30	0.35	ns
SSTL18_I	SSTL_1.8 class I	0.01	0.01	0.01	ns
SSTL18D_I	Differential SSTL_1.8 class I	0.01	0.01	0.01	ns
LVTTTL33_4mA	LVTTTL 4mA drive	0.09	0.11	0.13	ns
LVTTTL33_8mA	LVTTTL 8mA drive	0.07	0.08	0.09	ns
LVTTTL33_12mA	LVTTTL 12mA drive	-0.03	-0.04	-0.05	ns
LVTTTL33_16mA	LVTTTL 16mA drive	0.36	0.43	0.51	ns
LVTTTL33_20mA	LVTTTL 20mA drive	0.28	0.33	0.39	ns
LVC MOS33_4mA	LVC MOS 3.3 4mA drive	0.09	0.11	0.13	ns
LVC MOS33_8mA	LVC MOS 3.3 8mA drive	0.07	0.08	0.09	ns
LVC MOS33_12mA	LVC MOS 3.3 12mA drive	-0.03	-0.04	-0.05	ns
LVC MOS33_16mA	LVC MOS 3.3 16mA drive	0.36	0.43	0.51	ns
LVC MOS33_20mA	LVC MOS 3.3 20mA drive	0.28	0.33	0.39	ns
LVC MOS25_4mA	LVC MOS 2.5 4mA drive	0.18	0.21	0.25	ns
LVC MOS25_8mA	LVC MOS 2.5 8mA drive	0.10	0.12	0.14	ns
LVC MOS25_12mA	LVC MOS 2.5 12mA drive	0.00	0.00	0.00	ns
LVC MOS25_16mA	LVC MOS 2.5 16mA drive	0.22	0.26	0.31	ns
LVC MOS25_20mA	LVC MOS 2.5 20mA drive	0.14	0.16	0.19	ns
LVC MOS18_4mA	LVC MOS 1.8 4mA drive	0.15	0.18	0.21	ns
LVC MOS18_8mA	LVC MOS 1.8 8mA drive	0.06	0.08	0.09	ns
LVC MOS18_12mA	LVC MOS 1.8 12mA drive	0.01	0.01	0.01	ns
LVC MOS18_16mA	LVC MOS 1.8 16mA drive	0.16	0.19	0.22	ns
LVC MOS15_4mA	LVC MOS 1.5 4mA drive	0.26	0.31	0.36	ns
LVC MOS15_8mA	LVC MOS 1.5 8mA drive	0.04	0.04	0.05	ns
LVC MOS12_2mA	LVC MOS 1.2 2mA drive	0.36	0.43	0.50	ns
LVC MOS12_6mA	LVC MOS 1.2 6mA drive	0.08	0.10	0.11	ns
LVC MOS12_4mA	LVC MOS 1.2 4mA drive	0.36	0.43	0.50	ns
PCI33	PCI33	1.05	1.26	1.46	ns

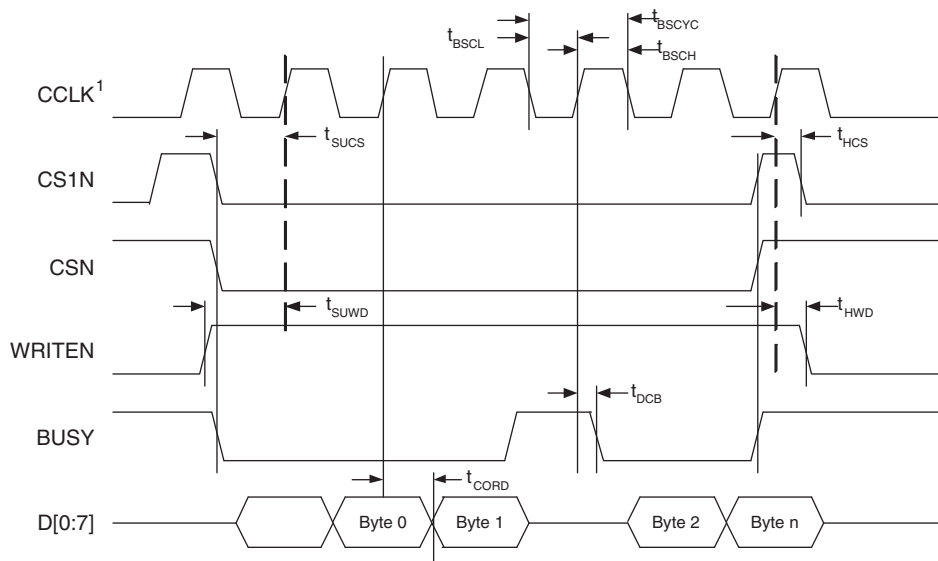
1. Timing adders are characterized but not tested on every device.

2. LVC MOS timing measured with the load specified in Switching Test Conditions table of this document.

3. All other standards according to the appropriate specification.

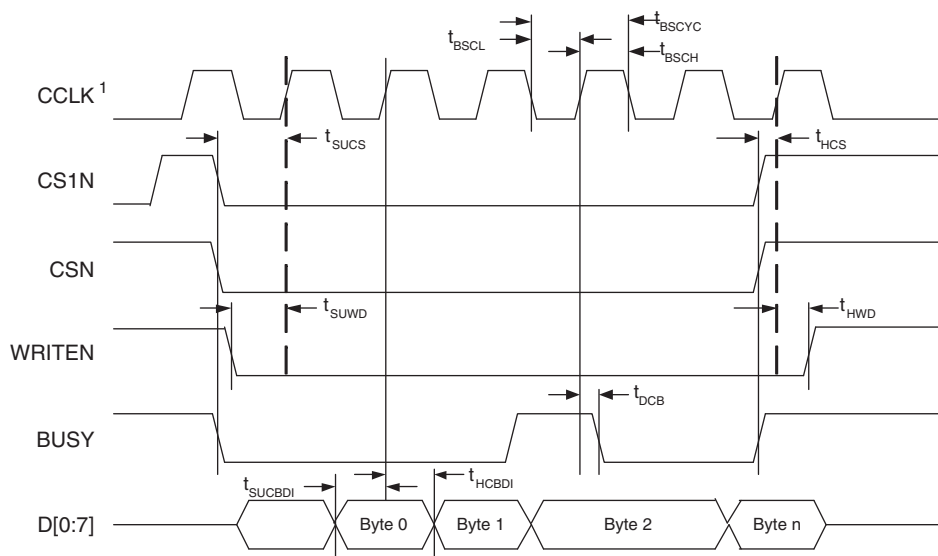
Timing v.G 0.30

Figure 3-12. sysCONFIG Parallel Port Read Cycle



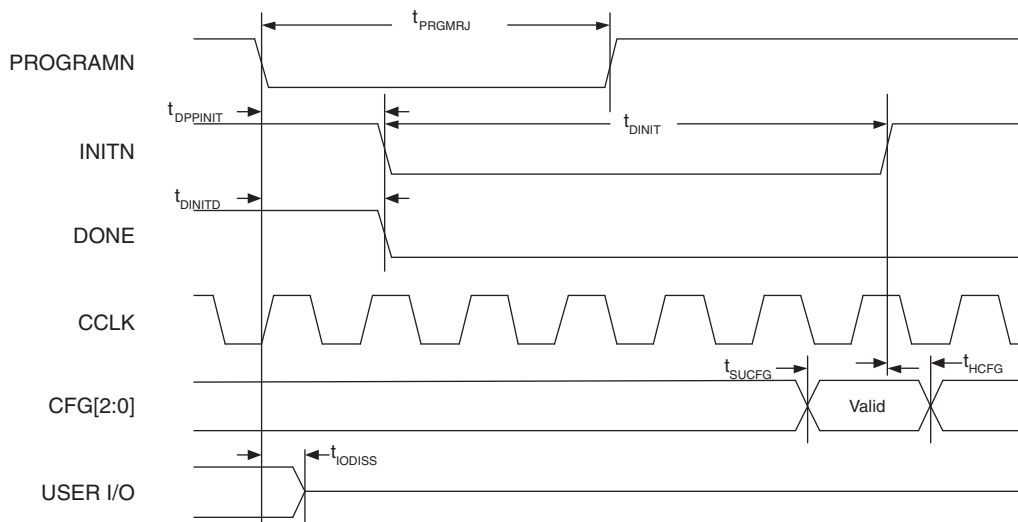
1. In Master Parallel Mode the FPGA provides CCLK. In Slave Parallel Mode the external device provides CCLK.

Figure 3-13. sysCONFIG Parallel Port Write Cycle



1. In Master Parallel Mode the FPGA provides CCLK. In Slave Parallel Mode the external device provides CCLK.

Figure 3-17. Configuration from PROGRAMN Timing



1. The CFG pins are normally static (hard wired)

Figure 3-18. Wake-Up Timing

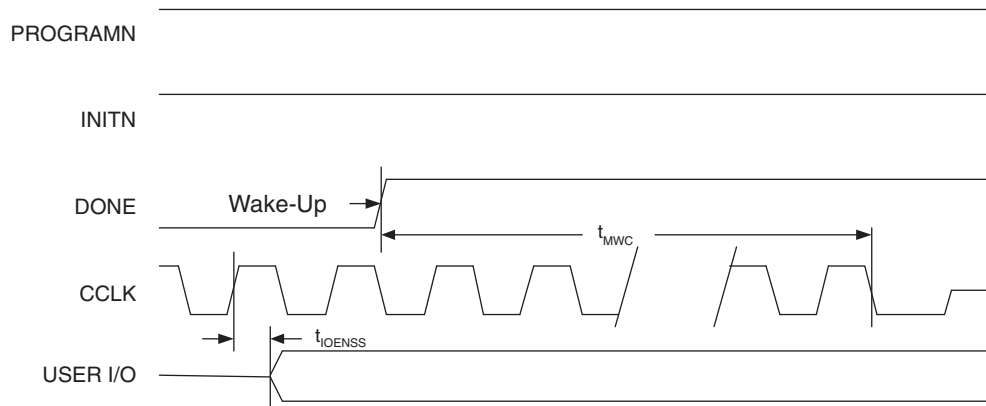
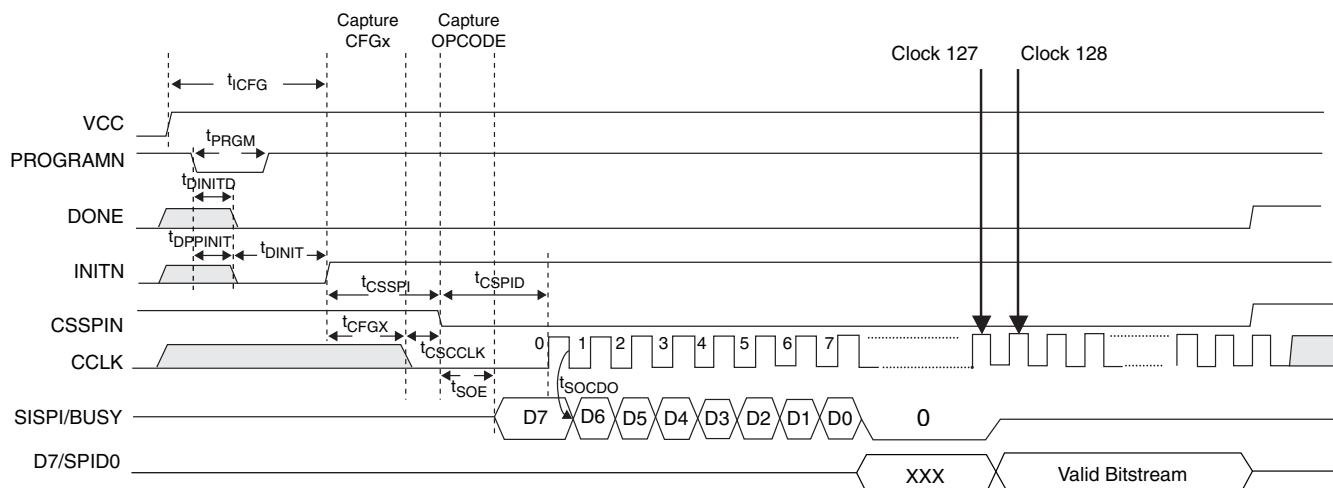


Figure 3-19. sysCONFIG SPI Port Sequence



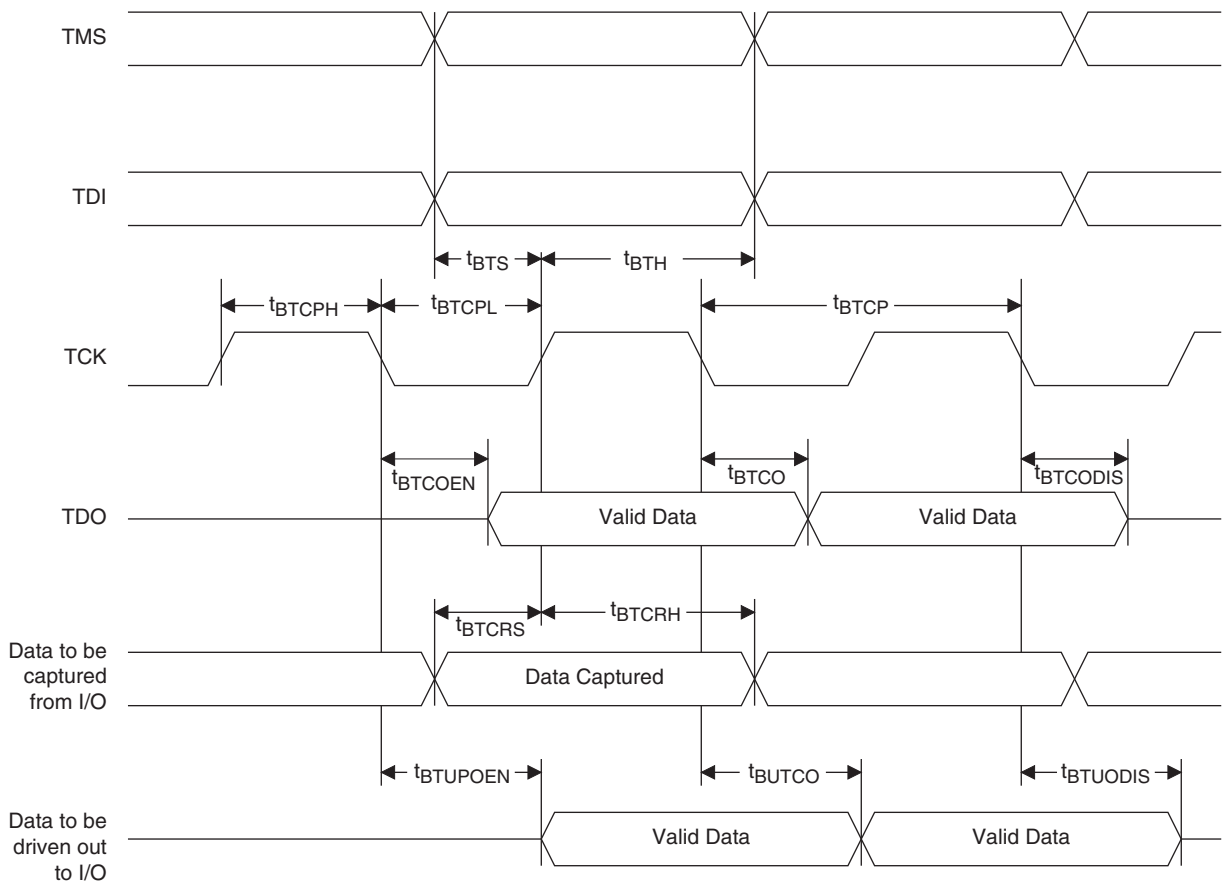
JTAG Port Timing Specifications

Over Recommended Operating Conditions

Symbol	Parameter	Min	Max	Units
f_{MAX}	TCK clock frequency	—	25	MHz
t_{BTCP}	TCK [BSCAN] clock pulse width	40	—	ns
t_{BTCPH}	TCK [BSCAN] clock pulse width high	20	—	ns
t_{BTCPL}	TCK [BSCAN] clock pulse width low	20	—	ns
t_{BTS}	TCK [BSCAN] setup time	8	—	ns
t_{BTH}	TCK [BSCAN] hold time	10	—	ns
t_{BTRF}	TCK [BSCAN] rise/fall time	50	—	mV/ns
t_{BTCO}	TAP controller falling edge of clock to valid output	—	10	ns
$t_{BTCODIS}$	TAP controller falling edge of clock to valid disable	—	10	ns
t_{BTCOEN}	TAP controller falling edge of clock to valid enable	—	10	ns
t_{BTCRS}	BSCAN test capture register setup time	8	—	ns
t_{BTCRH}	BSCAN test capture register hold time	25	—	ns
t_{BUTCO}	BSCAN test update register, falling edge of clock to valid output	—	25	ns
$t_{BTUODIS}$	BSCAN test update register, falling edge of clock to valid disable	—	25	ns
$t_{BTUPOEN}$	BSCAN test update register, falling edge of clock to valid enable	—	25	ns

Timing v.G 0.30

Figure 3-20. JTAG Port Timing Waveforms



LFEC1, LFEC3 Logic Signal Connections: 208 PQFP (Cont.)

Pin Number	LFEC1				LFEC3			
	Pin Function	Bank	LVDS	Dual Function	Pin Function	Bank	LVDS	Dual Function
169	PT13A	1	T		PT21A	1	T	
170	PT12B	1	C		PT20B	1	C	
171	PT12A	1	T		PT20A	1	T	
172	PT11B	1	C	VREF2_1	PT19B	1	C	VREF2_1
173	PT11A	1	T	VREF1_1	PT19A	1	T	VREF1_1
174	PT10B	1	C		PT18B	1	C	
175	PT10A	1	T		PT18A	1	T	
176	VCCIO1	1			VCCIO1	1		
177	VCCAUX	-			VCCAUX	-		
178	PT9B	0	C	PCLKC0_0	PT17B	0	C	PCLKC0_0
179	GND0	0			GND0	0		
180	PT9A	0	T	PCLKT0_0	PT17A	0	T	PCLKT0_0
181	PT8B	0	C	VREF1_0	PT16B	0	C	VREF1_0
182	PT8A	0	T	VREF2_0	PT16A	0	T	VREF2_0
183	PT7B	0	C		PT15B	0	C	
184	PT7A	0	T		PT15A	0	T	
185	PT6B	0	C		PT14B	0	C	
186	PT6A	0	T	TDQS6	PT14A	0	T	TDQS14
187	VCCIO0	0			VCCIO0	0		
188	PT5B	0	C		PT13B	0	C	
189	NC	-			GND0	0		
190	PT5A	0	T		PT13A	0	T	
191	PT4B	0	C		PT12B	0	C	
192	PT4A	0	T		PT12A	0	T	
193	PT3B	0	C		PT11B	0	C	
194	PT3A	0	T		PT11A	0	T	
195	PT2B	0	C		PT10B	0	C	
196	PT2A	0	T		PT10A	0	T	
197	NC	-			VCCIO0	0		
198	NC	-			PT6B	0	C	
199	NC	-			PT6A	0	T	TDQS6
200	NC	-			PT5B	0	C	
201	NC	-			PT5A	0	T	
202	NC	-			PT4B	0	C	
203	NC	-			PT4A	0	T	
204	NC	-			PT3B	0	C	
205	NC	-			PT3A	0	T	
206	NC	-			PT2B	0	C	
207	NC	-			PT2A	0	T	
208	VCCIO0	0			VCCIO0	0		

* Double bonded to the pin.

LFEC3 and LFECP/EC6 Logic Signal Connections: 256 fpBGA

Ball Number	LFEC3				LFECP6/LFEC6			
	Ball Function	Bank	LVDS	Dual Function	Ball Function	Bank	LVDS	Dual Function
GND	GND7	7			GND7	7		
D4	PL2A	7	T	VREF2_7	PL2A	7	T	VREF2_7
D3	PL2B	7	C	VREF1_7	PL2B	7	C	VREF1_7
C3	PL3A	7	T		PL3A	7	T	
C2	PL3B	7	C		PL3B	7	C	
B1	PL4A	7	T		PL4A	7	T	
C1	PL4B	7	C		PL4B	7	C	
E3	PL5A	7	T		PL5A	7	T	
E4	PL5B	7	C		PL5B	7	C	
F4	PL6A	7	T	LDQS6	PL6A	7	T	LDQS6
F5	PL6B	7	C		PL6B	7	C	
G4	PL7A	7	T		PL7A	7	T	
G3	PL7B	7	C		PL7B	7	C	
D2	PL8A	7	T		PL8A	7	T	
D1	PL8B	7	C		PL8B	7	C	
E1	PL9A	7	T	PCLKT7_0	PL9A	7	T	PCLKT7_0
GND	GND7	7			GND7	7		
E2	PL9B	7	C	PCLKC7_0	PL9B	7	C	PCLKC7_0
F3	XRES	6			XRES	6		
G5	NC	-			PL11A	6	T	
H5	NC	-			PL11B	6	C	
F2	NC	-			PL12A	6	T	
F1	NC	-			PL12B	6	C	
H4	NC	-			PL13A	6	T	
H3	NC	-			PL13B	6	C	
G2	NC	-			PL14A	6	T	
-	-	-			GND6	6		
G1	NC	-			PL14B	6	C	
J4	NC	-			PL15A	6	T	LDQS15
J3	NC	-			PL15B	6	C	
J5	NC	-			PL16A	6	T	
K5	NC	-			PL16B	6	C	
H2	NC	-			PL17A	6	T	
H1	NC	-			PL17B	6	C	
J2	NC	-			PL18A	6	T	
-	-	-			GND6	6		
J1	NC	-			PL18B	6	C	
K4	TCK	6			TCK	6		
K3	TDI	6			TDI	6		
L3	TMS	6			TMS	6		
L5	TDO	6			TDO	6		
L4	VCCJ	6			VCCJ	6		

LFEC3 and LFEC6/EC6 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFEC3				LFEC6/EC6			
	Ball Function	Bank	LVDS	Dual Function	Ball Function	Bank	LVDS	Dual Function
GND	GND5	5			GND5	5		
T9	PB13B	5	C		PB13B	5	C	
P8	PB14A	5	T	BDQS14	PB14A	5	T	BDQS14
N8	PB14B	5	C		PB14B	5	C	
R9	PB15A	5	T		PB15A	5	T	
R10	PB15B	5	C		PB15B	5	C	
P9	PB16A	5	T	VREF2_5	PB16A	5	T	VREF2_5
N9	PB16B	5	C	VREF1_5	PB16B	5	C	VREF1_5
T10	PB17A	5	T	PCLKT5_0	PB17A	5	T	PCLKT5_0
GND	GND5	5			GND5	5		
T11	PB17B	5	C	PCLKC5_0	PB17B	5	C	PCLKC5_0
T12	PB18A	4	T	WRITEN	PB18A	4	T	WRITEN
T13	PB18B	4	C	CS1N	PB18B	4	C	CS1N
P10	PB19A	4	T	VREF1_4	PB19A	4	T	VREF1_4
N10	PB19B	4	C	CSN	PB19B	4	C	CSN
T14	PB20A	4	T	VREF2_4	PB20A	4	T	VREF2_4
T15	PB20B	4	C	D0/SPID7	PB20B	4	C	D0/SPID7
M10	PB21A	4	T	D2/SPID5	PB21A	4	T	D2/SPID5
GND	GND4	4			GND4	4		
M11	PB21B	4	C	D1/SPID6	PB21B	4	C	D1/SPID6
R11	PB22A	4	T	BDQS22	PB22A	4	T	BDQS22
P11	PB22B	4	C	D3/SPID4	PB22B	4	C	D3/SPID4
R13	PB23A	4	T		PB23A	4	T	
R14	PB23B	4	C	D4/SPID3	PB23B	4	C	D4/SPID3
P12	PB24A	4	T		PB24A	4	T	
P13	PB24B	4	C	D5/SPID2	PB24B	4	C	D5/SPID2
N11	PB25A	4	T		PB25A	4	T	
-	-	-			GND4	4		
N12	PB25B	4	C	D6/SPID1	PB25B	4	C	D6/SPID1
R12	NC	-			PB26A	4		
GND	GND4	4			GND4	4		
-	-	-			GND4	4		
GND	GND3	3			GND3	3		
N13	PR18B	3	C	VREF2_3	PR27B	3	C	VREF2_3
N14	PR18A	3	T	VREF1_3	PR27A	3	T	VREF1_3
P14	PR17B	3	C		PR26B	3	C	
P15	PR17A	3	T		PR26A	3	T	
R15	PR16B	3	C		PR25B	3	C	
R16	PR16A	3	T		PR25A	3	T	
M13	PR15B	3	C		PR24B	3	C	
M14	PR15A	3	T	RDQS15	PR24A	3	T	RDQS24
P16	PR14B	3	C	RLM0_PLLC_FB_A	PR23B	3	C	RLM0_PLLC_FB_A
GND	GND3	3			GND3	3		

LFEC3 and LFECP/EC6 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFEC3				LFECP6/LFEC6			
	Ball Function	Bank	LVDS	Dual Function	Ball Function	Bank	LVDS	Dual Function
E5	VCC	-			VCC	-		
E8	VCC	-			VCC	-		
M12	VCC	-			VCC	-		
M5	VCC	-			VCC	-		
M9	VCC	-			VCC	-		
B15	VCCAUX	-			VCCAUX	-		
R2	VCCAUX	-			VCCAUX	-		
F7	VCCIO0	0			VCCIO0	0		
F8	VCCIO0	0			VCCIO0	0		
F10	VCCIO1	1			VCCIO1	1		
F9	VCCIO1	1			VCCIO1	1		
G11	VCCIO2	2			VCCIO2	2		
H11	VCCIO2	2			VCCIO2	2		
J11	VCCIO3	3			VCCIO3	3		
K11	VCCIO3	3			VCCIO3	3		
L10	VCCIO4	4			VCCIO4	4		
L9	VCCIO4	4			VCCIO4	4		
L7	VCCIO5	5			VCCIO5	5		
L8	VCCIO5	5			VCCIO5	5		
J6	VCCIO6	6			VCCIO6	6		
K6	VCCIO6	6			VCCIO6	6		
G6	VCCIO7	7			VCCIO7	7		
H6	VCCIO7	7			VCCIO7	7		
F6	VCC	-			VCC	-		
F11	VCC	-			VCC	-		
L11	VCC	-			VCC	-		
L6	VCC	-			VCC	-		

LFEC10/EC10 and LFEC15/EC15 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFEC10/EC10				LFEC15/EC15			
	Ball Function	Bank	LVDS	Dual Function	Ball Function	Bank	LVDS	Dual Function
P14	PR35B	3	C		PR43B	3	C	
P15	PR35A	3	T		PR43A	3	T	
R15	PR34B	3	C		PR42B	3	C	
R16	PR34A	3	T		PR42A	3	T	
M13	PR33B	3	C		PR41B	3	C	
M14	PR33A	3	T	RDQS33	PR41A	3	T	RDQS41
P16	PR32B	3	C	RLM0_PLLC_FB_A	PR40B	3	C	RLM0_PLLC_FB_A
GND	GND3	3			GND3	3		
N16	PR32A	3	T	RLM0_PLLT_FB_A	PR40A	3	T	RLM0_PLLT_FB_A
N15	PR31B	3	C	RLM0_PLLC_IN_A	PR39B	3	C	RLM0_PLLC_IN_A
M15	PR31A	3	T	RLM0_PLLT_IN_A	PR39A	3	T	RLM0_PLLT_IN_A
M16	PR30B	3	C	DI/CSSPIN	PR38B	3	C	DI/CSSPIN
L16	PR30A	3	T	DOUT/CSON	PR38A	3	T	DOUT/CSON
K16	PR29B	3	C	BUSY/SISPI	PR37B	3	C	BUSY/SISPI
J16	PR29A	3	T	D7/SPID0	PR37A	3	T	D7/SPID0
L12	CFG2	3			CFG2	3		
L14	CFG1	3			CFG1	3		
L13	CFG0	3			CFG0	3		
K13	PROGRAMN	3			PROGRAMN	3		
L15	CCLK	3			CCLK	3		
K15	INITN	3			INITN	3		
K14	DONE	3			DONE	3		
GND	GND3	3			GND3	3		
H16	PR27B	3	C		PR31B	3	C	
-	-	-			GND3	3		
H15	PR27A	3	T		PR31A	3	T	
G16	PR26B	3	C		PR30B	3	C	
G15	PR26A	3	T		PR30A	3	T	
K12	PR25B	3	C		PR29B	3	C	
J12	PR25A	3	T		PR29A	3	T	
J14	PR24B	3	C		PR28B	3	C	
J15	PR24A	3	T	RDQS24	PR28A	3	T	RDQS28
F16	PR23B	3	C		PR27B	3	C	
GND	GND3	3			GND3	3		
F15	PR23A	3	T		PR27A	3	T	
J13	PR22B	3	C		PR26B	3	C	
H13	PR22A	3	T		PR26A	3	T	
H14	PR21B	3	C		PR25B	3	C	
G14	PR21A	3	T		PR25A	3	T	
E16	PR20B	3	C		PR24B	3	C	
E15	PR20A	3	T		PR24A	3	T	
H12	PR18B	2	C	PCLKC2_0	PR22B	2	C	PCLKC2_0
GND	GND2	2			GND2	2		

LFECP/EC20, LFECP/EC33 Logic Signal Connections: 672 fpBGA (Cont.)

LFEC20/LFECP20					LFECP/EC33				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
AF22	PB51A	4	T		AF22	PB51A	4	T	
AB17	PB51B	4	C		AB17	PB51B	4	C	
AE22	PB52A	4	T		AE22	PB52A	4	T	
AA18	PB52B	4	C		AA18	PB52B	4	C	
AE19	PB53A	4	T		AE19	PB53A	4	T	
GND	GND4	4			GND	GND4	4		
AE20	PB53B	4	C		AE20	PB53B	4	C	
AA19	PB54A	4	T	BDQS54	AA19	PB54A	4	T	BDQS54
Y18	PB54B	4	C		Y18	PB54B	4	C	
AF23	PB55A	4	T		AF23	PB55A	4	T	
AA20	PB55B	4	C		AA20	PB55B	4	C	
AC18	PB56A	4	T		AC18	PB56A	4	T	
AB18	PB56B	4	C		AB18	PB56B	4	C	
AF24	PB57A	4	T		AF24	PB57A	4	T	
-	-	-			GND	GND4	4		
AE23	PB57B	4	C		AE23	PB57B	4	C	
AD19	NC	-			AD19	PB58A	4	T	
AD20	NC	-			AD20	PB58B	4	C	
AC19	NC	-			AC19	PB59A	4	T	
AB19	NC	-			AB19	PB59B	4	C	
AD21	NC	-			AD21	PB60A	4	T	
AC20	NC	-			AC20	PB60B	4	C	
AF25	NC	-			AF25	PB61A	4	T	
-	-	-			GND	GND4	4		
AE25	NC	-			AE25	PB61B	4	C	
AB21	NC	-			AB21	PB62A	4	T	BDQS62
AB20	NC	-			AB20	PB62B	4	C	
AE24	NC	-			AE24	PB63A	4	T	
AD23	NC	-			AD23	PB63B	4	C	
AD22	NC	-			AD22	PB64A	4	T	
AC21	NC	-			AC21	PB64B	4	C	
AC22	NC	-			AC22	PB65A	4	T	
AB22	NC	-			AB22	PB65B	4	C	
GND	GND4	4			GND	GND4	4		
GND	GND3	3			GND	GND3	3		
AC23	PR48B	3	C	VREF2_3	AC23	PR68B	3	C	VREF2_3
AC24	PR48A	3	T	VREF1_3	AC24	PR68A	3	T	VREF1_3
AD24	NC	-			AD24	PR67B	3	C	
AD25	NC	-			AD25	PR67A	3	T	
AE26	NC	-			AE26	PR66B	3	C	
AD26	NC	-			AD26	PR66A	3	T	
Y20	NC	-			Y20	PR65B	3	C	

LFECP/EC20, LFECP/EC33 Logic Signal Connections: 672 fpBGA (Cont.)

LFEC20/LFECP20					LFECP/EC33				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
U21	PR36B	3	C		U21	PR48B	3	C	
T21	PR36A	3	T	RDQS36	T21	PR48A	3	T	RDQS48
T25	PR35B	3	C		T25	PR47B	3	C	
GND	GND3	3			GND	GND3	3		
T26	PR35A	3	T		T26	PR47A	3	T	
T22	PR34B	3	C		T22	PR46B	3	C	
T23	PR34A	3	T		T23	PR46A	3	T	
T24	PR33B	3	C		T24	PR45B	3	C	
R23	PR33A	3	T		R23	PR45A	3	T	
R25	PR32B	3	C		R25	PR44B	3	C	
R24	PR32A	3	T		R24	PR44A	3	T	
R26	PR31B	3	C		R26	PR43B	3	C	
GND	GND3	3			GND	GND3	3		
P26	PR31A	3	T		P26	PR43A	3	T	
R21	PR30B	3	C		R21	PR42B	3	C	
R22	PR30A	3	T		R22	PR42A	3	T	
P25	PR29B	3	C		P25	PR41B	3	C	
P24	PR29A	3	T		P24	PR41A	3	T	
P23	PR28B	3	C		P23	PR40B	3	C	
P22	PR28A	3	T	RDQS28	P22	PR40A	3	T	RDQS40
N26	PR27B	3	C		N26	PR39B	3	C	
GND	GND3	3			GND	GND3	3		
M26	PR27A	3	T		M26	PR39A	3	T	
N21	PR26B	3	C		N21	PR38B	3	C	
P21	PR26A	3	T		P21	PR38A	3	T	
N23	PR25B	3	C		N23	PR37B	3	C	
N22	PR25A	3	T		N22	PR37A	3	T	
N25	PR24B	3	C		N25	PR36B	3	C	
N24	PR24A	3	T		N24	PR36A	3	T	
L26	PR22B	2	C	PCLKC2_0	L26	PR34B	2	C	PCLKC2_0
GND	GND2	2			GND	GND2	2		
K26	PR22A	2	T	PCLKT2_0	K26	PR34A	2	T	PCLKT2_0
M22	PR21B	2	C		M22	PR33B	2	C	
M23	PR21A	2	T		M23	PR33A	2	T	
M25	PR20B	2	C		M25	PR32B	2	C	
M24	PR20A	2	T		M24	PR32A	2	T	
M21	PR19B	2	C		M21	PR31B	2	C	
L21	PR19A	2	T	RDQS19	L21	PR31A	2	T	RDQS31
L22	PR18B	2	C		L22	PR30B	2	C	
GND	GND2	2			GND	GND2	2		
L23	PR18A	2	T		L23	PR30A	2	T	
L25	PR17B	2	C		L25	PR29B	2	C	

LFECP/EC20, LFECP/EC33 Logic Signal Connections: 672 fpBGA (Cont.)

LFEC20/LFECP20					LFECP/EC33				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
L24	PR17A	2	T		L24	PR29A	2	T	
K25	PR16B	2	C		K25	PR28B	2	C	
J25	PR16A	2	T		J25	PR28A	2	T	
J26	PR15B	2	C		J26	PR27B	2	C	
H26	PR15A	2	T		H26	PR27A	2	T	
H25	PR14B	2	C		H25	PR26B	2	C	
GND	GND2	2			GND	GND2	2		
J24	PR14A	2	T		J24	PR26A	2	T	
K21	PR13B	2	C		K21	PR25B	2	C	
K22	PR13A	2	T		K22	PR25A	2	T	
K20	PR12B	2	C		K20	PR24B	2	C	
J20	PR12A	2	T		J20	PR24A	2	T	
K23	PR11B	2	C		K23	PR23B	2	C	
K24	PR11A	2	T		K24	PR23A	2	T	RDQS23
J21	NC	-			J21	PR22B	2	C	
-	-	-			GND	GND2	2		
J22	NC	-			J22	PR22A	2	T	
J23	NC	-			J23	PR21B	2	C	
H22	NC	-			H22	PR21A	2	T	
G26	NC	-			G26	PR20B	2	C	
F26	NC	-			F26	PR20A	2	T	
E26	NC	-			E26	PR19B	2	C	
E25	NC	-			E25	PR19A	2	T	
F25	PR9B	2	C	RUM0_PLLC_FB_A	F25	PR17B	2	C	RUM0_PLLC_FB_A
GND	GND2	2			GND	GND2	2		
G25	PR9A	2	T	RUM0_PLLT_FB_A	G25	PR17A	2	T	RUM0_PLLT_FB_A
H23	PR8B	2	C	RUM0_PLLC_IN_A	H23	PR16B	2	C	RUM0_PLLC_IN_A
H24	PR8A	2	T	RUM0_PLLT_IN_A	H24	PR16A	2	T	RUM0_PLLT_IN_A
H21	PR7B	2	C		H21	PR15B	2	C	
G21	PR7A	2	T		G21	PR15A	2	T	
D26	PR6B	2	C		D26	PR14B	2	C	
D25	PR6A	2	T	RDQS6	D25	PR14A	2	T	RDQS14
F21	PR5B	2	C		F21	PR13B	2	C	
-	-	-			GND	GND2	2		
G22	PR5A	2	T		G22	PR13A	2	T	
G24	PR4B	2	C		G24	PR12B	2	C	
G23	PR4A	2	T		G23	PR12A	2	T	
C26	PR3B	2	C		C26	PR11B	2	C	
C25	PR3A	2	T		C25	PR11A	2	T	
F24	NC	-			F24	PR9B	2	C	
-	-	-			GND	GND2	2		
F23	NC	-			F23	PR9A	2	T	

LatticeEC Industrial (Continued)

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFEC15E-3FN484I	352	-3	Lead-Free fpBGA	484	IND	15.3K
LFEC15E-4FN484I	352	-4	Lead-Free fpBGA	484	IND	15.3K
LFEC15E-3FN256I	195	-3	Lead-Free fpBGA	256	IND	15.3K
LFEC15E-4FN256I	195	-4	Lead-Free fpBGA	256	IND	15.3K

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFEC20E-3FN672I	400	-3	Lead-Free fpBGA	672	IND	19.7K
LFEC20E-4FN672I	400	-4	Lead-Free fpBGA	672	IND	19.7K
LFEC20E-3FN484I	400	-3	Lead-Free fpBGA	484	IND	19.7K
LFEC20E-4FN484I	400	-4	Lead-Free fpBGA	484	IND	19.7K

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFEC33E-3FN672I	496	-3	Lead-Free fpBGA	672	IND	32.8K
LFEC33E-4FN672I	496	-4	Lead-Free fpBGA	672	IND	32.8K
LFEC33E-3FN484I	360	-3	Lead-Free fpBGA	484	IND	32.8K
LFEC33E-4FN484I	360	-4	Lead-Free fpBGA	484	IND	32.8K

LatticeECP Industrial

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFEC6E-3FN484I	224	-3	Lead-Free fpBGA	484	IND	6.1K
LFEC6E-4FN484I	224	-4	Lead-Free fpBGA	484	IND	6.1K
LFEC6E-3FN256I	195	-3	Lead-Free fpBGA	256	IND	6.1K
LFEC6E-4FN256I	195	-4	Lead-Free fpBGA	256	IND	6.1K
LFEC6E-3QN208I	147	-3	Lead-Free PQFP	208	IND	6.1K
LFEC6E-4QN208I	147	-4	Lead-Free PQFP	208	IND	6.1K
LFEC6E-3TN144I	97	-3	Lead-Free TQFP	144	IND	6.1K
LFEC6E-4TN144I	97	-4	Lead-Free TQFP	144	IND	6.1K

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFEC10E-3FN484I	288	-3	Lead-Free fpBGA	484	IND	10.2K
LFEC10E-4FN484I	288	-4	Lead-Free fpBGA	484	IND	10.2K
LFEC10E-3FN256I	195	-3	Lead-Free fpBGA	256	IND	10.2K
LFEC10E-4FN256I	195	-4	Lead-Free fpBGA	256	IND	10.2K
LFEC10E-3QN208I	147	-3	Lead-Free PQFP	208	IND	10.2K
LFEC10E-4QN208I	147	-4	Lead-Free PQFP	208	IND	10.2K

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFEC15E-3FN484I	352	-3	Lead-Free fpBGA	484	IND	15.3K
LFEC15E-4FN484I	352	-4	Lead-Free fpBGA	484	IND	15.3K
LFEC15E-3FN256I	195	-3	Lead-Free fpBGA	256	IND	15.3K
LFEC15E-4FN256I	195	-4	Lead-Free fpBGA	256	IND	15.3K